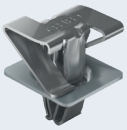
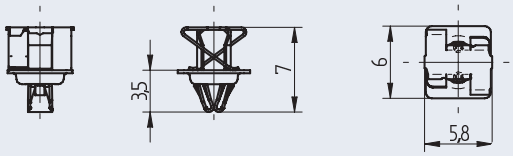
P2F - Fixing Elements

28.904 · SMD-P2F - Solderable fixing element for linear LED modules

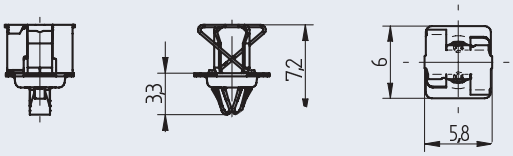
technology for light

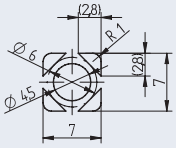


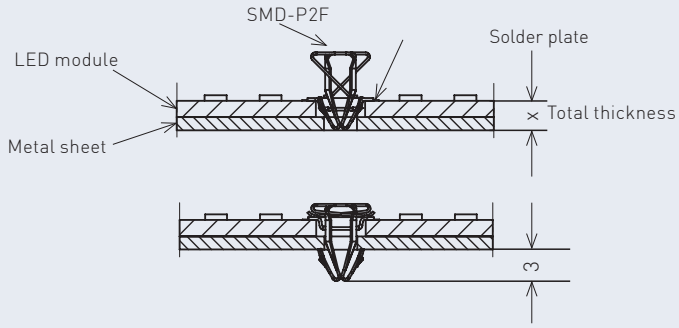
28.904.U101.10



28.904.U102.10







SMD-P2F (Push-to-Fix) – solderable fixing element

For simplified final installation of linear LED modules by means of pre-attached P2F

Push fixing for linear LED modules
Material: Spring: CrNi
Solder plate: CuSn

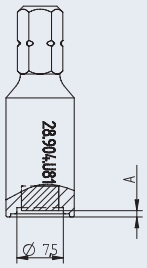
Total thickness **28.904.**U101.10 (x): 1.5 - 2.6 mm

Total thickness **28.904.**U102.10 (x): 1.8 - 2.9 mm

- No additional screw-fixing assembly required
- Permanent, constant contact pressure with a minimum pressure force of 5 N
- Suitable for standardized hole patterns with ø 4.5 mm in the LED module
- For luminaire metal sheet cut-out: ø 3,0 $^{+0,2}$ mm
- Reliable heat dissipation due to constant contact pressure
- Suitable for manual and automatic final installation
- Automated assembly solution on request
- Low-profile component prevents shadowing
- Alternative to screw fixing => no torque screwdriver required
- Quick installation process increases productivity and reduces production costs
- Tape and reel packaging
- Low insertion force prevents possible damage which may occur with screw fixing
- Releasable connection

Accessories:
Magnetic bit für **28.904.**U101.10

28.904.U811.10	Total thickness: 2.4 - 2.6 mm	A = 1.0 mm
28.904.U812.10	Total thickness: 1.8 - 2.3 mm	A = 1.5 mm
28.904.U813.10	Total thickness: 1.5 - 1.7 mm	A = 2.0 mm

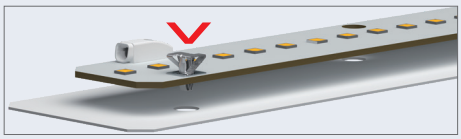


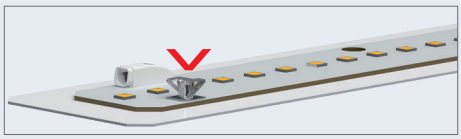
Magnetic bit for **28.904.**U102.10

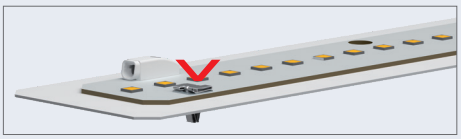
28.904.U811.10	Total thickness: 2.7 - 2.9 mm	A = 1.0 mm
28.904.U812.10	Total thickness: 2.1 - 2.6 mm	A = 1.5 mm
28.904.U813.10	Total thickness: 1.8 - 2.0 mm	A = 2.0 mm

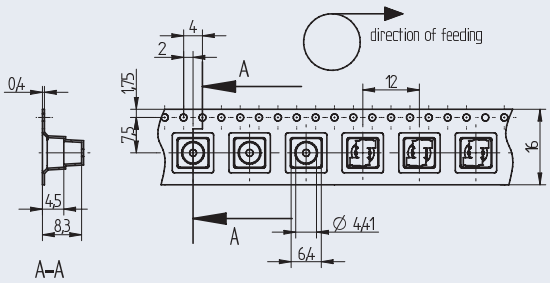
Bit holder **28.901.**U801.89

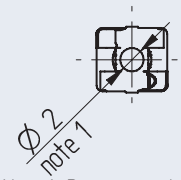
Example of application:



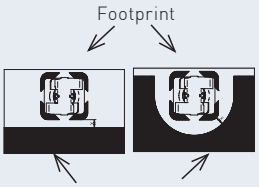








Note 1: Recommended Pick and Place area



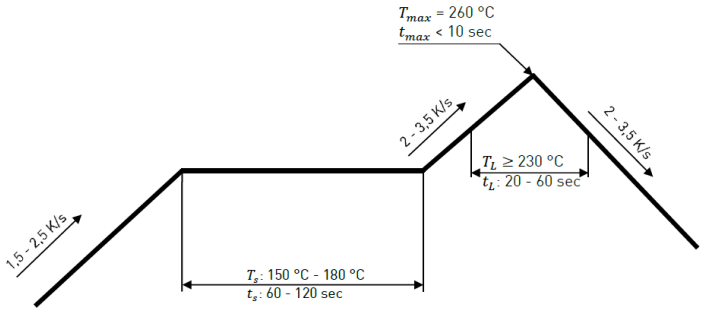
Current carrying copper surfaces/circuit path

Creepage and clearance distances

The SMD-P2F fixing element has direct contact with the metal work of the luminary via the metallic spring clip.

The distance "X" is therefore dependent on the applicable standard, the luminaire class (luminaire application) and the required creepage and clearance distances for this purpose and must be observed accordingly.

Important processing notes

Storage time	Solderability up to 6 months when stored between -5°C and +40°C and rel. humidity between 10...60% r H. After a storage time of 6 months, solderability has to be checked according to J-STD-002D or DIN EN 60068-2-58:2016.
max. allowed number of reflow-processes	3
Reflow-profile	Reflow-profile (lead-free) 
Solderability	Solderability of components is checked by wetting test according to J-STD-002D
Assembly method	SMD, according to drawing
Recommended solder stencil thickness	100 - 150 µm (recommendation BJB 150)

Cut-out for appliction in aluminium profiles with profile holes